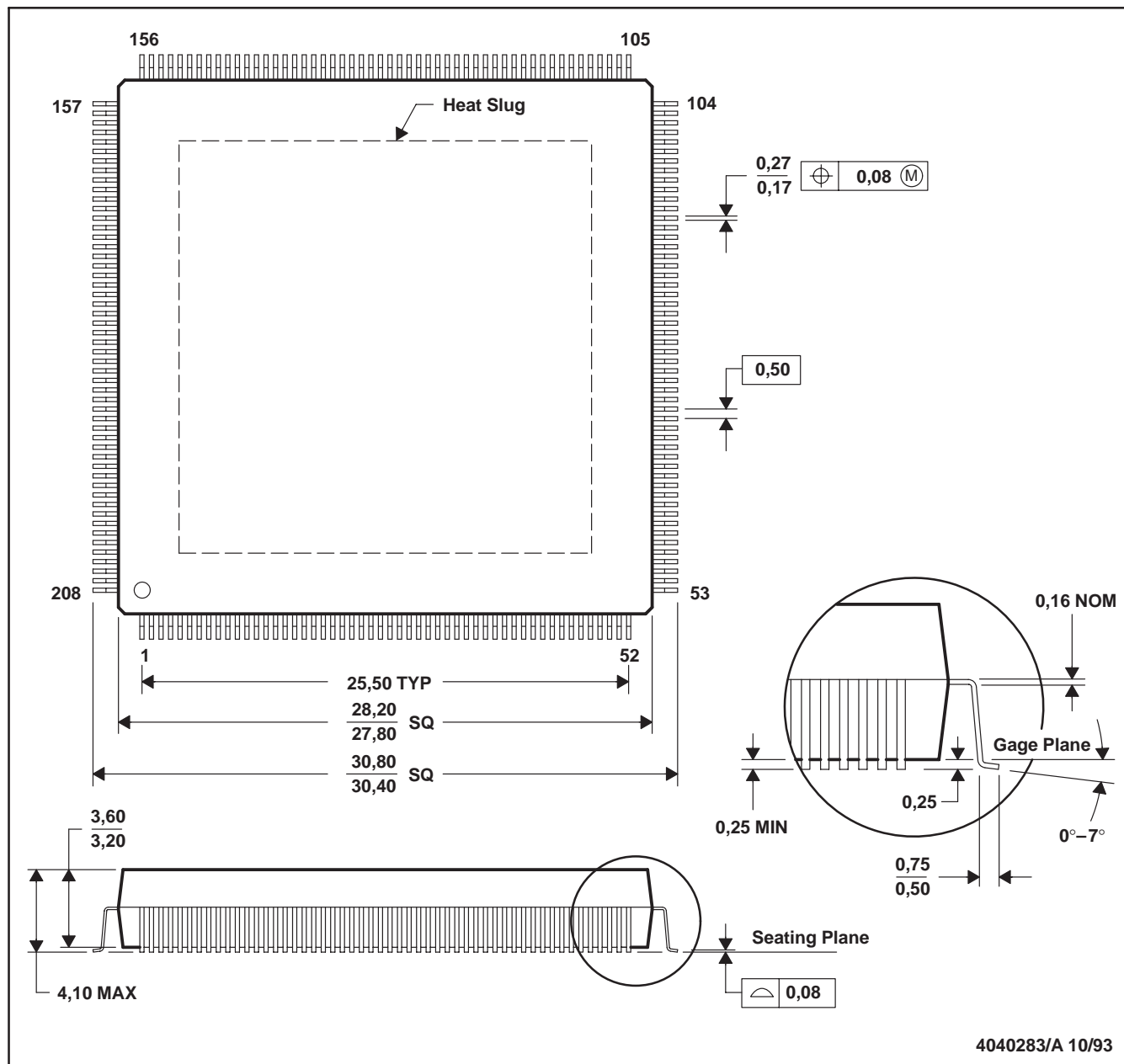


## PPA (S-PQFP-G208)

## PLASTIC QUAD FLATPACK



- NOTES:
- All linear dimensions are in millimeters.
  - This drawing is subject to change without notice.
  - Thermally enhanced molded plastic package with a heat slug (HSL).
  - Falls within JEDEC MO-143

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